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November 21, 2001

Box PATENT APPLICATION

Commissioner for Patents Washington, D.C. 20231

Re: New U.S. Patent Appln. Our Ref: 381NP/5067

Sir:

Transmitted herewith for filing is the patent application of:

Hiroyuki KADOTA

entitled:

ELECTROLYTIC GOLD PLATING METHOD AND APPARATUS THEREFOR

Enclosed are:

- 1. Specification, including <u>16</u> claims (pages <u>25</u>, plus specification front page).
- 2. <u>4</u> Sheets of <u>X</u> Formal _ Informal drawings showing Figs. 1-5.
- 3. <u>X</u> Declaration and Power of Attorney (executed).
- 4. Assignment of the invention to <u>Hitachi Kyowa Engineering Co., Ltd.</u>
- 5. The filing fee has been calculated as shown below:

Basic Fee							\$370/740	= \$740.00
Total Claims	30	<u>-</u>	20	= _	10	X	\$9/18	= \$180.00
Independent Claims	9	<u>-</u>	3	=	6	x	\$42/84	= \$504.00
Multiple Dependent Claim Presented						\$140/280	= \$280.00	
Total Filing Fee								\$1,704.00

Respectfully submitted,

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JFM:WAZ:vca



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PATENT TRADEMARK OFFICE